

PATENT ABSTRACTS OF JAPAN

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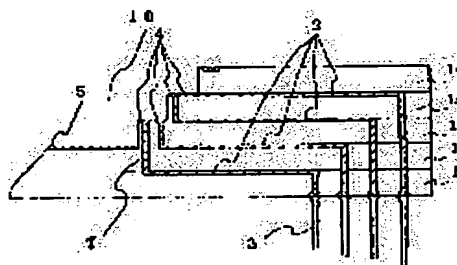
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(54) SEMICONDUCTOR PACKAGE**(57)Abstract:**

PURPOSE: To increase the number of terminals, and to manufacture a semiconductor package proper to the improvement of the degree of integration by forming a vertical conductor section vertically connected to a bonding pad section just under the bonding pad section and connecting an internal wiring pattern at another end of the vertical conductor section.

CONSTITUTION: Bonding pad sections 4 are connected to vertical conductor sections 7 on the sides where outer lead pins 3 are connected through internal wiring patterns 2. The vertical conductor sections 7 correspond to the arrangement of the outer lead pins 3, have length different at every row, and are connected to the internal wiring patterns 2 on different planes.

Consequently, a plural row of the bonding pad sections 4 are arranged on the same plane, the bonding pad sections 4 can be disposed onto a plural step of different planes, and the number of the bonding pad sections 4 can be increased largely without changing the external shape of a semiconductor package and the size of a semiconductor-element receiving hole and the like. Accordingly, a semiconductor package proper to a semiconductor device having the high degree of integration can be manufactured.

**LEGAL STATUS**

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